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To: United States Patent and Trademark Office

Date: February 24, 2003

Attention: Examiner Leonardo Andujar

Re: U.S. Utility Patent Application
Appl. No. 09/783,034; Filed: February 15, 2001

For: Die-Down Ball Grid
Array Package With Die-
Attached Heat Spreader
and Method for Making
the Same

From: Jeffrey S. Weaver

Inventors: Khan *et al.*

Pages (including cover sheet): 61 Pages

Our Reference: 1875.0210000/JSW

Fax No: 703 746 4118

Message

Examiner Andujar,

Pursuant to our telephone conversation earlier today, we are submitting copies to you by facsimile of the following documents previously submitted to the USPTO, along with copies of corresponding postcards date stamped by the USPTO:

1. Amendment and Reply submitted June 26, 2002;
2. Supplemental Information Disclosure Statement and accompanying PTO-1449 form submitted August 30, 2002; and
3. Information Disclosure Statement and accompanying PTO-1449 form submitted June 26, 2002.

Certification of Facsimile Transmission
I hereby certify that this paper is being facsimile transmitted
to the Patent and Trademark Office on the date shown below.


Amy D. Wise

Date: 2/24/2003

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Applicants: Khan *et al*
Application No.: 09/783,034
Filed: February 15, 2001
For: Die-Down Ball Grid Array Package with Die-Attached Heat Spreader and Method for Making the Same (As Amended)

Due Date: June 26, 2002
Art Unit: 2826
Examiner: Andujar, L.
Docket: 1875.0210000
Atty: JSW/LGK

When receipt stamp is placed hereon, the USPTO acknowledges receipt of the following documents:

1. SKGF Cover Letter;
2. Fee Transmittal Form PTO/SB/17;
3. Amendment And Reply Under 37 C.F.R. § 1.111;
4. Information Disclosure Statement;
5. Form PTO-1449 with (105) attached documents;
6. Return post card; and
7. Our Check No. 35656 for \$654.00 to cover:
\$474.00 for additional claims fee; and
\$180.00 for late submission of an Information Disclosure Statement.



Please Date Stamp And Return To Our Courier

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Amendment A
6/26/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Khan *et al.*

Appl. No. 09/783,034

Filed: February 15, 2001

For: **Die-Down Ball Grid Array
Package with Die-Attached Heat
Spreader and Method for Making
the Same (As Amended)**

Confirmation No.: 5713

Art Unit: 2826

Examiner: Andujar, L.

Atty. Docket: 1875.0210000

Amendment And Reply Under 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In reply to the Office Action dated **March 26, 2002**, (PTO Prosecution File Wrapper Paper No. 2), Applicants submit the following Amendment and Remarks. This Amendment is provided in the following format:

- (A) A clean version of each replacement paragraph/section/claim along with clear instructions for entry;
- (B) Starting on a separate page, appropriate remarks and arguments; 37 C.F.R. § 1.121 and MPEP 714; and
- (C) Starting on a separate page, a marked-up version entitled: "Version with markings to show changes made."

It is not believed that extensions of time or fees for net addition of claims are required beyond those that may otherwise be provided for in documents accompanying this paper. However, if additional extensions of time are necessary to prevent

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Khan *et al.*
Appl. No. 09/783,034

abandonment of this application, then such extensions of time are hereby petitioned under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to our Deposit Account No. 19-0036.

Amendments

In the Title:

Please substitute the following Title of the Invention for the pending Title of the Invention:

Die-Down Ball Grid Array Package with Die-Attached Heat Spreader and

A1 Method for Making the Same.

In the Claims:

Please amend claims 1-15, 17-25, 27-32, and 34-36 as follows:

1.(Amended) A ball grid array (BGA) package, comprising:

a stiffener;

A2 a substrate that has a first surface and a second surface, wherein said substrate has a central window-shaped aperture that extends through said substrate from said first surface of said substrate to said second surface of said substrate, wherein said first